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Integrated circuits – EMC evaluation of CAN transceivers

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INTEGRATED CIRCUITS – EMC EVALUATION OF CAN TRANSCEIVERS

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Technical specifications are subject to review within three years of publication to decide whether they can be transformed into International Standards.

IEC 62228, which is a technical specification, has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this technical specification is based on the following documents:

Enquiry draft	Report on voting
47A/747/DTS	47A/761/RVC

Full information on the voting for the approval of this technical specification can be found in the report on voting indicated in the above table.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- transformed into an international standard;
- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTEGRATED CIRCUITS − EMC EVALUATION OF CAN TRANSCEIVERS

1 Scope

This document specifies test and measurement methods, test conditions, test setups, test procedures, failure criteria and test signals for the EMC evaluation of CAN transceivers concerning:

- the immunity against RF common mode disturbances on the signal lines,
- the emissions caused by non-symmetrical signals regarding the time and frequency domain,
- the immunity against transients (function and damage), and
- the immunity against electrostatic discharges – ESD (damage).

All measurements and functional tests except ESD are performed in a small (three transceiver) network. For ESD damage tests a single transceiver configuration on a special test board is used.

External protection circuits are not applied during the tests in order to get results for the transceiver IC only.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61967 (all parts), *Integrated circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz*

IEC 61967-4, *Integrated circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz – Part 4: Measurement of conducted emissions – 1 Ω /150 Ω direct coupling method*

IEC 62132 (all parts), *Integrated circuits – Measurement of electromagnetic immunity, 150 kHz to 1 GHz*

IEC 62132-1, *Integrated circuits – Measurement of electromagnetic immunity, 150 kHz to 1 GHz – Part 1: General conditions and definitions*

IEC 62132-4, *Integrated circuits –Measurement of electromagnetic immunity 150 kHz to 1 GHz – Part 4: Direct RF Power Injection Method*

IEC 61000-4-2:1995, *Electromagnetic compatibility – Part 4: Testing and measurement techniques – Section 2: Electrostatic discharge immunity test*[1)]
Amendment 1 (1998)
Amendment 2 (2000)

ISO 7637-2: 2004, *Road vehicles – Electrical disturbances from conduction and coupling – Part 2: Electrical transient conduction along supply lines only*

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[1)] A consolidated edition 1.2 exists, including IEC 61000-4-2:1995 and its Amendment 1 (1998) and Amendment 2 (2000)